

ABSTRACT

5 A solid or semi-solid thermoplastic adhesive
adhered to a surface mount electronic device; an
assembly made of at least a printed circuit board, a
surface mount electronic device, solder joints
providing a connection between the printed circuit
board and the device, and solid thermoplastic
adhesive joints attached to the device and the
10 board. The thermoplastic adhesive is at least
softened and applied to any available surface on the
connecting substrate of the surface mounted
electronic device. The thermoplastic adhesive is
heated to a temperature sufficient to provide an
15 adhesive joint between the organic surface and the
board. There is also provided a thermoplastic
adhesive composition having at least the following
components:

20 (A) from 5% to 98% by weight of a functionalized
polyolefin, and

(B) from 2% to 95% by weight of a polyamide
compound.